



**CHENMKO ENTERPRISE CO.,LTD**

**Halogen free devices**

**SURFACE MOUNT**

**FAST SWITCHING DIODE**

**VOLTAGE RANGE 250 Volts CURRENT 200 mAmpere**

**BAS21HGP**

#### FEATURES

- \* Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- \* For surface mounted applications
- \* Low profile package
- \* Built-in strain relief
- \* Low power loss, high efficiency
- \* High current capability, low forward voltage drop
- \* Power dissipation: 150mW
- \* Repetitive peak forward surge current: 625mA
- \* High temperature soldering guaranteed : 260°C/10 seconds at terminals

#### MECHANICAL DATA

**Case:** JEDEC SC-76 molded plastic

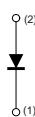
**Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity:** Color band denotes cathode end

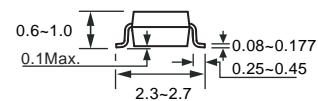
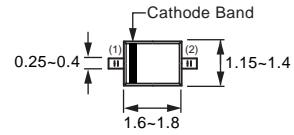
#### MARKING

\* X9

#### CIRCUIT



**SC-76/SOD-323**



Dimensions in millimeters

**SC-76/SOD-323**

#### MAXIMUM RATINGS ( At TA = 25°C unless otherwise noted )

RATINGS	SYMBOL	BAS21HGP	UNITS
Maximum Recurrent Peak Reverse Voltage	VR <sub>RM</sub>	250	Volts
Maximum RMS Voltage	VR <sub>MS</sub>	141	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	200	Volts
Maximum Average Forward Rectified Current at TL = 100°C	I <sub>O</sub>	200	mAmps
Non-Repetitive Peak Forward Surge Current @ t=1.0uS @ t=1.0S	I <sub>FSM</sub>	2.5 0.5	Amps
Typic Junction Capacitance (Note 2)	C <sub>J</sub>	5.0	pF
Maximum Reverse Recovery Time (Note 3)	T <sub>RR</sub>	50	ns
Typical Thermal Resistance (Note 1)	R <sub>θJA</sub>	833	°C / W
Storage and Operating Temperature Range	T <sub>J</sub> , T <sub>TG</sub>	-65 to +150	°C

#### ELECTRICAL CHARACTERISTICS ( At TA = 25°C unless otherwise noted )

CHARACTERISTICS	SYMBOL	BAS21HGP	UNITS
Maximum Instantaneous Forward Voltage @ I <sub>F</sub> = 100 mA @ I <sub>F</sub> = 200 mA	V <sub>F</sub>	1.00	Volts
		1.25	Volts
Maximum Average Reverse Current at Rated DC Blocking Voltage @ TA = 25°C @ TJ = 100°C	I <sub>R</sub>	100	nAmps
		15	uAmps
Breakdown Voltage(Minimum)	B <sub>v</sub>	250	Volts

NOTES : 1. Thermal Resistance ( Junction to Lead ) : PC Board Mounted on 0.06 X 0.06" ( 0.15X 0.15mm ) copper pad area.  
2. Measured at 1.0 MHz and applied reverse voltage of 0 volt.  
3. I<sub>F</sub>=I<sub>R</sub>=30 mA, I<sub>RR</sub>=0.1XI<sub>R</sub>, R<sub>L</sub>=100 ohms

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## RATING CHARACTERISTIC CURVES ( BAS21HGP )

FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURVE

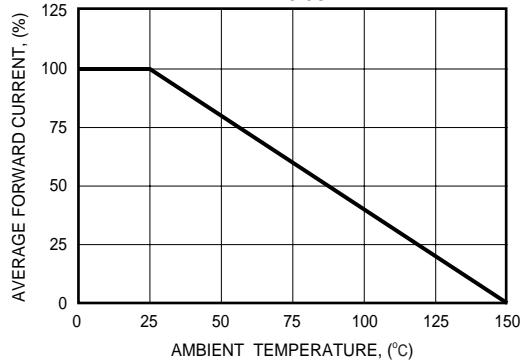


FIG. 2 - FORWARD CHARACTERISTICS

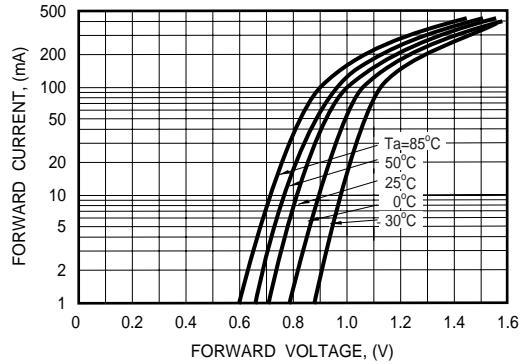


FIG. 3 - TYPICAL JUNCTION CAPACITANCE

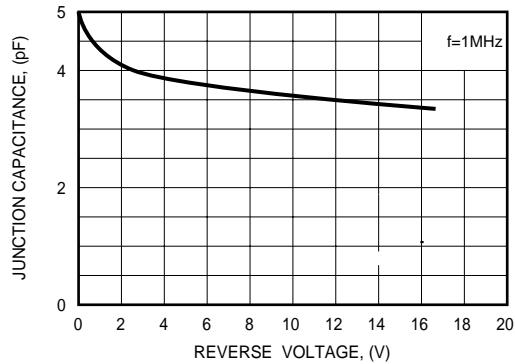


FIG. 4 - REVERSE CHARACTERISTICS

